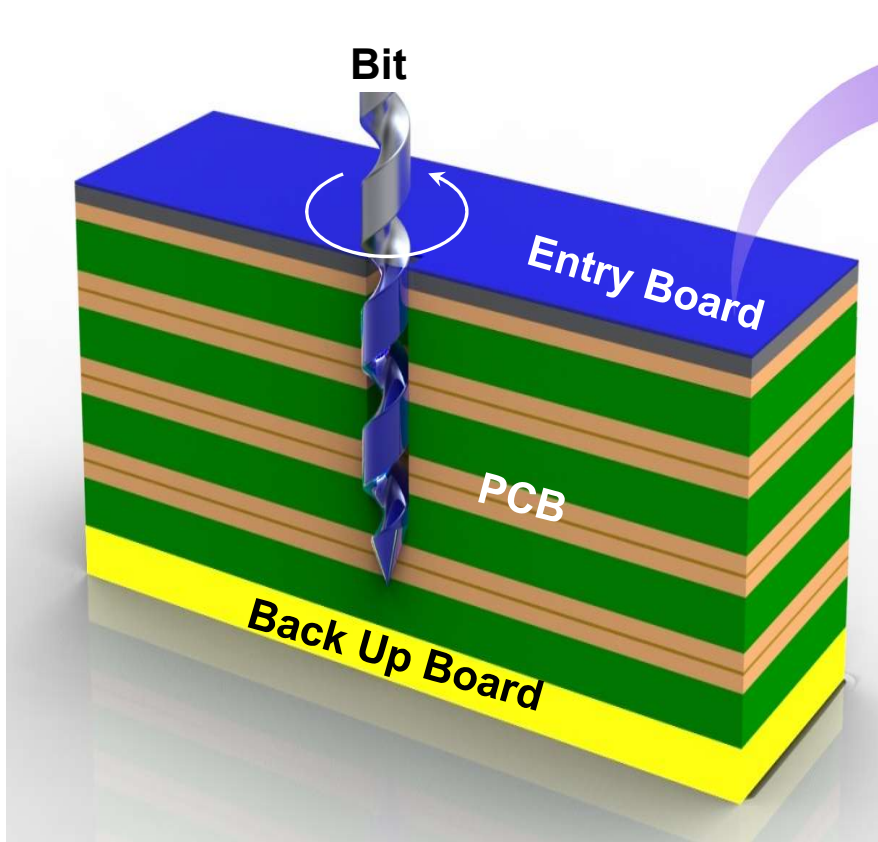


Topoint Lubricant Entry Board

Discipline, Insistence, Innovation

Topoint Technology

Entry Board for Drilling



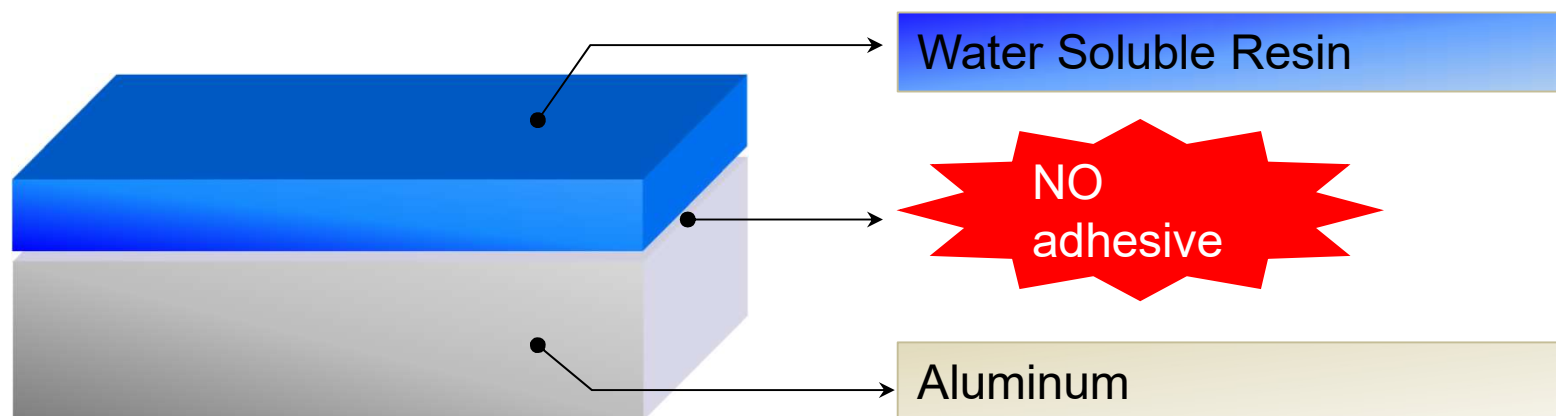
Key Factor

- Heat Discharge
- Chip Removal
- Bird Nesting
- Hole Accuracy
- Hole Roughness
- Stack Up

TAW Composition



- ❖ There is NO adhesive between Resin and AL



TAW Comparison

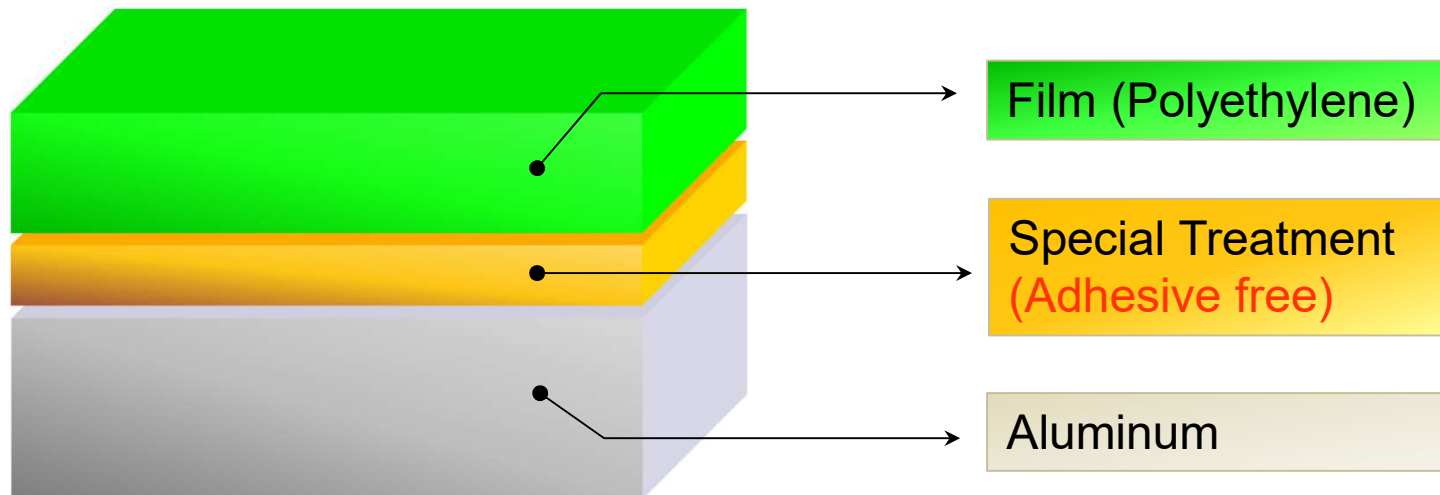


	Existing Type	TAW Grade
Process	Two Coating Process (Resin + Adhesive) ⇒ Bird Nesting ⇒ Bit Breakage	One Coating Process (Resin only)
Resin Property	Quick Crystallization (Hard Surface) ⇒ Hole Accuracy <input type="checkbox"/> ⇒ Hole Quality <input type="checkbox"/>	Slow Crystallization (Soft Surface) (Lubrication Up)

TAR Composition



- ❖ Special treatment (Adhesive free) between Polyethylene film and AL



TAR Comparison



	Existing Type	TAR Grade
Process	Dry / Heat Lamination (Adhesive) ⇒ Bird Nesting ⇒ Bit Breakage	Extrusion Lamination (Adhesive free)

Current Product Line



	TAW-100	TAR-180
Application	IC Substrate / Package	PCB
Drill Diameter	Φ 0.075 ~ Φ 0.15	Φ 0.2 ~ Φ 0.35
Resin Type	Water Soluble	Non Water Soluble
Aluminum Alloy	AA 1235 H18	AA 1235 H18
Total Thickness	100±10 um	180±18 um
	(AL.70 um / R.30 um)	(AL.120 um / R.60 um)
Color	Blue	Gray
Melting Point	70°C	105°C

Patent issue



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- 11:Dril bits
- 21:Water Soluble Resin
- 22:NoneWater Soluble Resin
- 23:Aluminum
- 31: Backup

